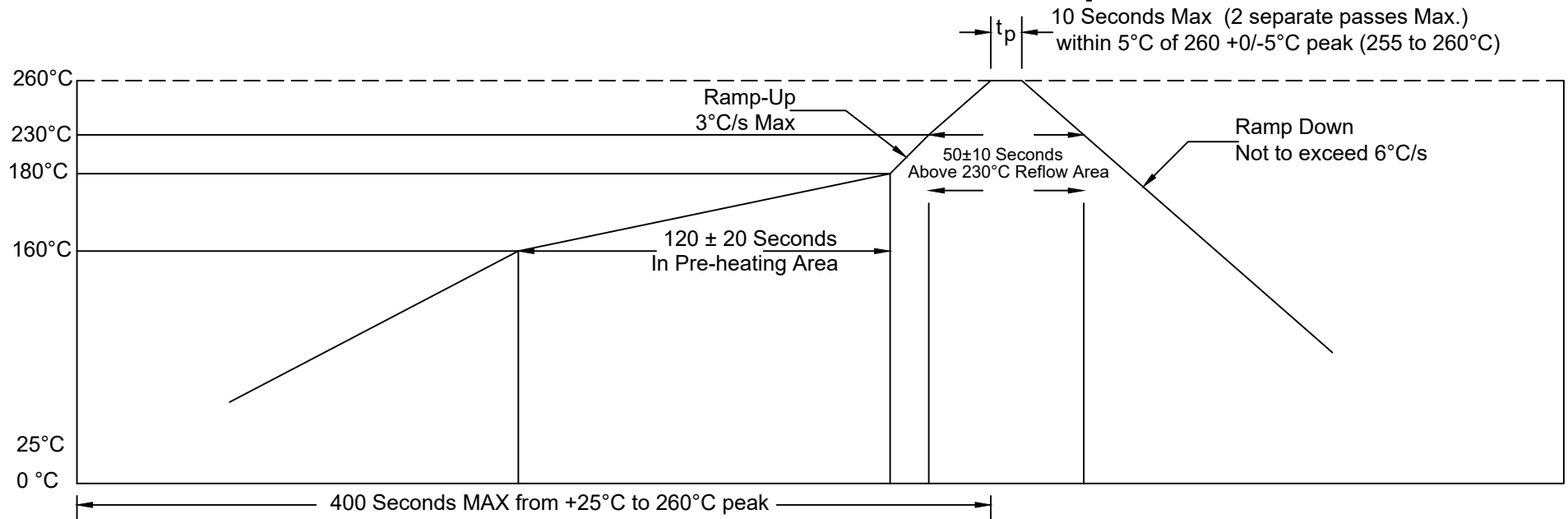


Pb-Free Reflow Graph



NOTES :

- 1) ALL Fox Electronics devices are hermetically sealed
JEDEC Moisture Sensitivity Level does not apply
(If a number is required, use MSL = 1)
- 2) Hand Soldering / Rework should be accomplished in < 4 Seconds
using an iron heated to a temperature no higher than 350°C
Check other recommendations (# 4 & # 6) before any Rework
- 3) Termination Finish for Ceramic SMD devices
is Au over Ni underplating
- 4) Termination Finish for packages C1BQ, C3BQ, C5AQ, and C5BQ
is Fired Ag Paste, not recommended for rework
- 5) Termination Finish for HC49 crystal packages
is Sn-Ag-Cu over Ni underplate over Kovar
- 6) Termination Finish for Plastic encapsulated SMD devices
is 100% matte Sn. (Not recommended for rework)



DRAWING FILE #: DWG-5060	COMMENT See NOTES: in DWG
DATE Mar 15, 2019	AUTHOR Alan Reinmiller
TITLE Pb-Free Reflow Graph	